



Material Content Data Sheet



Sales Product Name		TLE6208-6G		Issued		16. September 2015		
MA#		MA001406854						
Package		PG-DSO-28-41		Weight*		835.34 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.425	1.73	1.73	17268	17268
leadframe	inorganic material	phosphorus	7723-14-0	0.073	0.01		87	
	non noble metal	zinc	7440-66-6	0.292	0.03		349	
	non noble metal	iron	7439-89-6	5.837	0.70		6988	
wire	non noble metal	copper	7440-50-8	237.007	28.37	29.11	283726	291150
	non noble metal	copper	7440-50-8	1.263	0.15	0.15	1512	1512
	encapsulation	organic material	carbon black	1333-86-4	1.131	0.14		1354
encapsulation	plastics	epoxy resin	-	52.045	6.23		62304	
	inorganic material	silicondioxide	60676-86-0	512.526	61.34	67.71	613555	677213
leadfinish	non noble metal	tin	7440-31-5	4.975	0.60	0.60	5955	5955
plating	noble metal	silver	7440-22-4	1.897	0.23	0.23	2271	2271
glue	plastics	epoxy resin	-	0.967	0.12		1158	
	noble metal	silver	7440-22-4	2.901	0.35	0.47	3473	4631
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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